

AMD Embedded Solutions

Product Selection Guide

AMD Embedded Solutions

Product Selection Guide

AMD64 Reference Design Kits																		
Name	Processor Support	Chipset	Form Factor	Topology	OS		I/O Connectors									Electrical/Mechanical		
					Windows® XP/Vista	Linux®	Display	Ethernet	Aux Slots	IDE	SAS	SATA	Audio	USB	Serial	Standard	NEBS	Compliance
Second-Generation AMD Opteron™ Processor-based AdvancedTCA® Blade	AMD Opteron™ Model 2210 EE Processor	Broadcom HT-2100, HT-1000	ATCA® Blade	Dual Star Backplane or 5 slot Full Mesh	●			Dual IG to Fabric, Dual IG to Base	AMC® x2 Half Height	●				2	1	Core Specification PICMG 3.0	NEBS Level-3 and ETSI installations	RoHS Compliant
AMD Socket S1 Processor COM Express	AMD Turion™ 64 X2, Mobile AMD Sempron™ Processors	AMD M690T/E with ATI Radeon™ X1250 Graphics	COM Express Type 2	N/A	●	●	DVI, LVDS, Analog VGA, TV	IG	3x1 PCIe®, 1x8 PCIe, PCI	2Ch		4	HD	8		COM-0		RoHS Compliant
AMD Socket AM2 Processor Storage Bridge Bay	AMD Athlon™ and AMD Athlon™ X2 Processors	Broadcom HT-2100, HT-1000	SBB 2.0	N/A		●	Analog VGA	GBE to back plate, GBE to mid-plane	1x8 PCIe	●	●	●		1	1	SBB 2.0		RoHS Compliant
AMD Sempron™ 210U/200U Processor Mini-DTX	ABSI BGA Processors	AMD M690E with ATI Radeon™ X1250 Graphics	Mini-DTX	N/A	●	●	DVI VGA	IG	2x1 PCIe	●		2	HD	6		Mini-DTX		RoHS Compliant

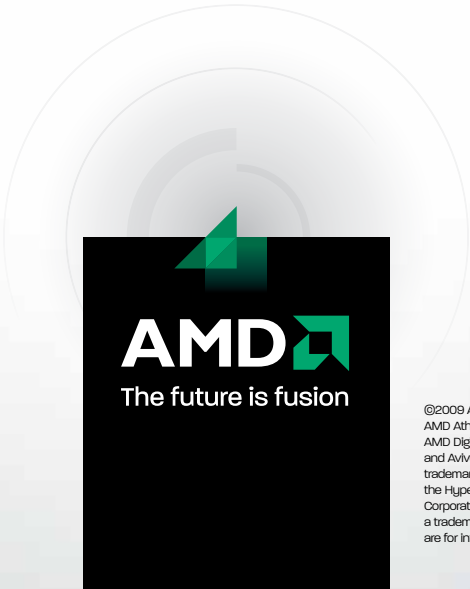
AMD Development Boards																											
Name	Processor (* Denotes Processor shipped in kit)	Chipset	Form Factor	Display Output	OS ¹					I/O Connectors															Typical Kit Contents		
					Windows® XP/xPe	Windows CE 4.2	Windows CE 5.0	Linux® 2.4x	Linux 2.6x	Audio Out Channels	USB	PCI Express® Slots	PCI Express Mini Card	PCI Slots	Mini-PCI	LPC Slots or Headers	Super I/O on Board	Ethernet on Board	Power	Serial ATA	IDE UDMA	Serial Ports	PS/2 Keyboard/Mouse	Parallel Port	I/OA	DVI/HDMI Adapter Board	CD-ROM/Std. Documentation
AMD GEODE™ SOLUTIONS BASED DEVELOPMENT BOARDS																											
LX DB800	AMD Geode™ LX 800@0.9W ²	AMD C5536	Mini-ITX/ETX	CRT, TFT	●	●		●	2	4				1 ³		1	1	1	ATX		●	3	1	1	1	●	
AMD64 BASED DEVELOPMENT BOARDS																											
S1 DBM690T/E	Mobile AMD Sempron™ 3500+* and 2800+, AMD Turion™ 64 X2 TL-52, AMD Sempron 200+	AMD M690T or M690E, SB600	ATX	CRT, DVI/HDMI, LVDS	●			●	71	9	1x16 ¹ 1x1	●	3	●	1	1	1	ATX	4	●	1	1	1		●		
AM2+ DB780E	AMD Phenom™ 9350a, AMD Athlon™ X2 4200+ and 3400a, AMD Athlon 3100+ and 2000+	AMD 780E	µATX	CRT/DVI	●			●	71	12	1x16, 1x4		1			1	1	ATX	6	●	1				●		

Notes 1. OS support typically includes BIOS and drivers for audio, display, and bootloader if required.
Note 2. The Geode LX 800@0.9W processor operates at 500MHz. Model numbers reflect performance as described here: <http://www.amd.com/connected/it/solutions/geode/benchmark>. DDR2 versions available - please talk with your AMD representative.
Note 3. The Geode LX DB900 has one 32-bit, 66/33MHz, 3.3V (non-5V tolerant) PCI slot. Additionally, a bridge card that offers two 32-bit, 66/33MHz, 3.3V (5V tolerant) slots is shipped with the development board. The bridge card occupies the one slot on the main board.
Note 4. The S1 DBM690T/E has one x16 PCI Express® slot that is supported by a 1x8 PCI Express interface.

About AMD

AMD (NYSE:AMD) designs and produces innovative microprocessors and low-power processor solutions for the computer, communications, and consumer electronics industries. AMD is dedicated to delivering standards-based, customer-focused solutions for technology users, ranging from enterprises and governments to individual consumers. www.amd.com.

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A rich mix of high-performance, low-power processors to meet the fast time-to-market demands of today's embedded systems

Along with a range of varied processors, AMD supports the x86 embedded marketplace with design tools, support, and partnerships that offer simplicity and flexibility to create high-performance, feature-rich, and customer-driven products.

AMD is an innovation leader in x86 processor design. AMD's embedded products offer designers processor-level features and a balanced foundation for overall system performance with the quick time-to-market offered by commercial off-the-shelf components. Customers using AMD processor-based systems can experience remarkable application performance with scalability, ease of management, and low total cost of ownership. AMD processor-based products are category leaders from enterprise-class servers and cutting-edge consumer systems to traditional embedded markets.

This brochure presents the full array of AMD's embedded processor solutions that deliver maximum performance with low overall system power consumption and are supported by longer than standard availability, a full library of x86 software development applications, and hardware tools. It's time to design and produce the next-generation embedded systems your customers demand — quickly, easily, and efficiently.

AMD's unique processor designs deliver high performance and balanced system design

- AMD's range of embedded solutions provides flexible features and a balanced performance approach for the overall system. Features include:
- Industry-leading performance-per-watt
 - Highest available I/O throughput with HyperTransport™ technology
 - Integrated memory controller offers low latency and reduced chip count, improving reliability
 - Native quad-core processor design provides highly scalable performance gains within a consistent thermal envelope
 - Lead-free, four-layer processes with maximum on-board space
 - Efficient heat dissipation reduces or eliminates the need for heat sinks and reduces ambient cooling requirements
 - Range of available packaging and pin counts meets variety of design requirements

Along with these features and other technical features, embedded designers can count on long-term component availability, comprehensive design support, and AMD's commitment to continue offering new, customer-oriented products. Get to market faster with more effective products.

The AMD64 embedded family: leading-edge technology for high-end embedded systems

AMD64 embedded solutions are each uniquely matched to a defined set of product applications. Ranging from high-performance single-, dual- and quad-core AMD Opteron™ and single- and dual-core AMD Athlon™ processor with Direct Connect Architecture for enterprise-class storage and networking equipment to highly versatile and efficient Mobile AMD Sempron™ processors and AMD Turion™ 64 X2 Dual-core mobile technology for unique high-performance, smaller form factor applications, the AMD64 family provides high performance, maximum versatility, and minimum design challenge.

AMD Geode™ processors: optimized for low-power, high-performance applications

AMD Geode™ processors are configured to give developers a versatile and flexible suite of x86 solutions that enable fast design cycles and short time-to-market roadmaps. Ideal for applications ranging from thin-client and set-top boxes to printers and personal media players.

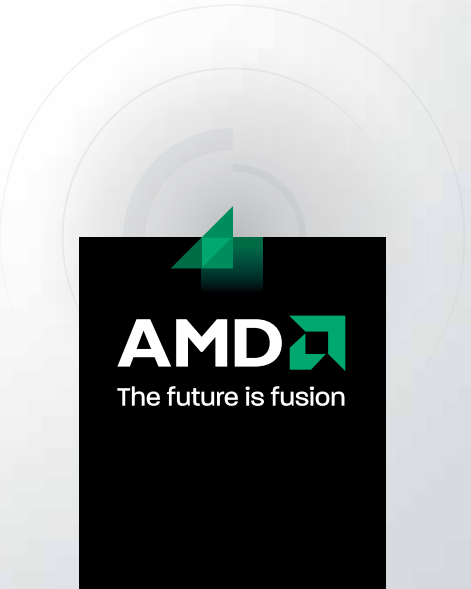
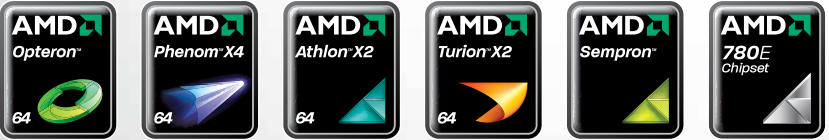
AMD Geode processors can deliver the highest performance-per-watt in the industry. In addition to processors, the family includes a broad range of design tools including Development Boards (DBs) and Reference Design Kits (RDks) to empower designers to make maximum use of the established world of x86 software applications.

Tools and support for developers

- AMD offers:
- A full range of RDK products that enable designers to go from concept to finished product quickly
 - A broad array of DBs for creating efficient x86 system designs
 - Industry partnerships with leading software and hardware specialists, fostering maximum choice for your unique design

Get better systems to market faster with AMD embedded solutions

Ready to create high-performance, low-power embedded designs that give your innovative new products an edge in the marketplace? Take a close look and experience the AMD advantage.



AMD Embedded Solutions

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Dual-Core AMD Opteron™ Processors															
Model	OPN	AMD64	Multi-CPU Scalability	Core Frequency	L2 Cache/ Core	Thermal Design Power	Memory Interface	HyperTransport™ Technology	AMD Digital Media Xpress™ Technology	AMD PowerNow™ Technology	AMD-V™ Technology	EVP¹	Tcase	Socket	Package
8214 EE	OSP8214GAU6CYE	Yes	up to 8	2.2GHz	1MB x2	68W	Dual 64/72 DDR2-667 Registered DIMMs, EEC & Chip Kill	Three 16-lane@1GHz Full Duplex	Yes	Yes	Yes	Yes	83°C	F(1207)	Udded 1207 pad LGA
8210 EE	OSH8210GAU6CYE	Yes	up to 8	1.8GHz	1MB x2	45W	Dual 64/72 DDR2-667 Registered DIMMs, EEC & Chip kill	Three 16-lane@1GHz Full Duplex	Yes	Yes	Yes	Yes	80°C	F(1207)	Udded 1207 pad LGA
2214 EE	OSP2214GAU6CYE	Yes	up to 2	2.2GHz	1MB x2	68W	Dual 64/72 DDR2-667 Registered DIMMs, EEC & Chip Kill	Three 16-lane@1GHz Full Duplex	Yes	Yes	Yes	Yes	83°C	F(1207)	Udded 1207 pad LGA
2210 EE	OSH2210GAU6CYE	Yes	up to 2	1.8GHz	1MB x2	45W	Dual 64/72 DDR2-667 Registered DIMMs, EEC & Chip Kill	Three 16-lane@1GHz Full Duplex	Yes	Yes	Yes	Yes	80°C	F(1207)	Udded 1207 pad LGA
2208 EE	OSP2208GAU6CYE	Yes	up to 2	1.8GHz	512KB x2	68W	Dual 64/72 DDR2-667 Registered DIMMs, EEC & Chip Kill	Three 16-lane@1GHz Full Duplex	Yes	Yes	Yes	Yes	78°C	F(1207)	Udded 1207 pad LGA
1214 HE	OSP1214GAU6CYE	Yes	1	2.2GHz	1MB x2	68W	Dual 64/72 DDR2-667 Registered DIMMs, EEC & Chip Kill	Three 16-lane@1GHz Full Duplex	Yes	Yes	Yes	Yes	83°C	F(1207)	Udded 1207 pad LGA
1210 EE	OSHI210GAU6CYE	Yes	1	1.8GHz	1MB x2	45W	Dual 64/72 DDR2-667 Registered DIMMs, EEC & Chip Kill	Three 16-lane@1GHz Full Duplex	Yes	Yes	Yes	Yes	80°C	F(1207)	Udded 1207 pad LGA

AMD Opteron™ Processors															
Model	OPN	AMD64	Multi-CPU Scalability	Core Frequency	L2 Cache/ Core	Thermal Design Power	Memory Interface	HyperTransport™ Technology	AMD Digital Media Xpress™ Technology	AMD PowerNow!™ Technology	AMD-V™ Technology	EVP¹	Tcase	Socket	Package
2204 EE	2204GA4DTE	Yes	up to 2	1.8GHz	512KB	45W	Dual 64/72 DDR2-667 Registered DIMMs, EEC & Chip Kill	Three 16-lane@1GHz Full Duplex	Yes	Yes	Yes	Yes	76° C	F(1207)	Udded 1207 pad LGA

AMD Athlon™ X2 Dual-Core Processors															
Model	OPN	AMD64	Multi-CPU Scalability	Core Frequency	L2 Cache/ Core	Thermal Design Power	Memory Interface	HyperTransport™ Technology	AMD Digital Media Xpress™ Technology	AMD PowerNow!™ Technology	AMD-V™ Technology	EVP¹	Tcase	Socket	Package
4200+	ADD4200IAASDOE	Yes	1	2.2GHz	512KB x2	35W	Dual 64 ECC DDR2-800, Unbuffered	One 16-lane@1000MHz Full Duplex	Yes	Yes	Yes	Yes	Var.	AM2	Udded 940-pin oµPGA
3600+	ADD3600IAASDOE	Yes	1	1.9GHz	512KB x2	35W	Dual 64 ECC DDR2-800, Unbuffered	One 16-lane@1000MHz Full Duplex	Yes	Yes	Yes	Yes	Var.	AM2	Udded 940-pin oµPGA
3400e	ADJ3400IAASDOE	Yes	1	1.8/1.0GHz²	512KB x2	22/10.8W²	Dual 64 ECC DDR2-800, Unbuffered	One 16-lane@1000MHz Full Duplex	Yes	Yes	Yes	Yes	Var.	AM2	Udded 940-pin oµPGA

AMD Athlon™ Processors															
Model	OPN	AMD64	Multi-CPU Scalability	Core Frequency	L2 Cache/ Core	Thermal Design Power	Memory Interface	HyperTransport™ Technology	AMD Digital Media Xpress™ Technology	AMD PowerNow!™ Technology	AMD-V™ Technology	EVP¹	Tcase	Socket	Package
3100+	ADS3100IA4RDRE	Yes	1	2.0GHz	512KB	25W	Dual 64 ECC DDR2-667, Unbuffered	One 16-lane@1000MHz Full Duplex	Yes	Yes	Yes	Yes	81°C	AM2	Udded 940-pin oµPGA
3000+	ADD3000IAA4CNE	Yes	1	1.8GHz	512KB	35W	Dual 64 ECC DDR2-667, Unbuffered	One 16-lane@1000MHz Full Duplex	Yes	Yes	Yes	Yes	Var.	AM2	Udded 940-pin oµPGA
2600+	ADG2600IAV4DRE	Yes	1	1.6GHz	512KB	15W	Dual 64 ECC DDR2-667, Unbuffered	One 16-lane@1000MHz Full Duplex	Yes	Yes	Yes	Yes	85°C	AM2	Udded 940-pin oµPGA
2000+	ADF2000IAV4DRE	Yes	1	1.0GHz	512KB	8W	Dual 64 ECC DDR2-400, Unbuffered	One 16-lane@1000MHz Full Duplex	Yes	No	Yes	Yes	85°C	AM2	Udded 940-pin oµPGA

Note 1. As part of a comprehensive security program, AMD strongly recommends enabling Enhanced Virus Protection (EVP) and using up to date third party anti-virus software.

Note 2. While operating at the max/min P-states which can be dynamic or fixed through BIOS.

AMD EMBEDDED PROCESSORS CONTINUED															
AMD Turion™ 64 X2 Dual-Core Mobile Technology															
Model	OPN	AMD64	Multi-CPU Scalability	Core Frequency	L2 Cache/ Core	Thermal Design Power	Memory Interface	HyperTransport™ Technology	AMD Digital Media Xpress™ Technology	AMD PowerNow™ Technology	AMD-V™ Technology	EVP	Tcase	Socket	Package
TL-62	TMDTL62HAX5DME	Yes	1	2.1GHz	512KB x2	35W	Dual 64 NON ECC DDR2-800, Unbuffered	One 16-lane@800MHz Full Duplex	Yes	Yes	Yes	Yes	95°C	Slgl	Lidless 638-pin oµPGA
TL-56	TMDTL56HAX5DME	Yes	1	1.8/0.8GHz²	512KB x2	31/9.4W²	Dual 64 NON ECC DDR2-800, Unbuffered	One 16-lane@800MHz Full Duplex	Yes	Yes	Yes	Yes	95°C	Slgl	Lidless 638-pin oµPGA

Note 1. While operating at the max/min P-States which can be dynamic or fixed through BIOS.

AMD Sempron™ Processors															
Model	OPN	AMD64	Multi-CPU Scalability	Core Frequency	L2 Cache/ Core	Thermal Design Power	Memory Interface	HyperTransport™ Technology	AMD Digital Media Xpress™ Technology	AMD PowerNow!™ Technology	AMD-V™ Technology	EVP	Tcase	Socket	Package
3700+	SMS3700HAX4DQE	Yes	1	2.0GHz	512KB	25W	Dual 64 NON ECC DDR2-667, Unbuffered	One 16-lane@800MHz Full Duplex	Yes	Yes	No	Yes	95°C	Slgl	Lidless 638-pin oµPGA
3500+	SMS3500HAX4CME	Yes	1	1.8GHz	512KB	25W	Dual 64 NON ECC DDR2-667, Unbuffered	One 16-lane@800MHz Full Duplex	Yes	Yes	No	Yes	95°C	Slgl	Lidless 638-pin oµPGA
2100+	SMF2100HAX3DQE	Yes	1	1.0GHz	256KB	8W	Dual 64 NON ECC DDR2-400, Unbuffered	One 16-lane@800MHz Full Duplex	Yes	No	No	Yes	95°C	Slgl	Lidless 638-pin oµPGA
210U	SMG210UQAX3DVE	Yes	1	1.5GHz	256KB	15W	64 NON ECC DDR2-667, Unbuffered	16-lane@800MHz Full Duplex	Yes	No	No	Yes	95°C	ASB1	Lidless 812-BGA
200U	SMF200UQAX3DVE	Yes	1	1.0GHz	256KB	8W	64 NON ECC DDR2-400, Unbuffered	16-lane@800MHz Full Duplex	Yes	No	No	Yes	95°C	ASB1	Lidless 812-BGA

Note 1. As part of a comprehensive security program, AMD strongly recommends enabling Enhanced Virus Protection (EVP) and using up to date third party anti-virus software.

AMD Geode™ Processors																						
Processor Family	Device Number	Chipset	Package/ Operating Case Temp.	Core Freq. (performance Rating)	Core Volt	Thermal Design Power	Power Management/ Rating	FPU	Memory Support	PCI	Ethernet	IDE	USB	LPC	Audio	UART/ IR	Serial/ Parallel Interfaces	RTC	Max. GPIOs	Security	Display: Max Resolution	
AMD Geode™ LX Processors (Integrated North Bridge/ Graphics) ¹	AMD Geode™ LX900@1.5W	AMD C5536	BGU481 0° C to 80° C	600MHz (900)	1.4V	5.1W	ACPI v2.0	MMX™, AMD 3DNow™ Technology	DDR400 ²	v2.2	No	1Ch., UDMA-100	4 Ports, v2.0	1 LDRQ	AC97 v2.3	2/1	ACCESS. bus w/2 Ports	1	32	28-Bit AES w/ Optional In-package EEPROM	CRT: 1920x1440 TFT: 1600x1200 VIP/VOP = 11,2.0	
	AMD Geode™ LX800@0.9W		BGU481 0° C to 85° C and -40° C to 85° C ²	500MHz (800)	1.25V	3.6W																DDR400 ³
	AMD Geode™ LX700@0.8W		BGU481 0° C to 85° C	433MHz (700)	1.2V	3.1W			DDR333 ³													
	AMD Geode™ LX600@0.7W		BGU481 0° C to 85° C	366MHz (600)	1.2V	2.8W			DDR266 ⁴											28-Bit AES		

Note 1. The Geode LX 900@1.5W processor operates at 600MHz, the Geode LX 800@0.9W processor operates at 500MHz, the Geode LX 700@0.8W processor operates at 433MHz, and the Geode LX800@0.7W processor operates at 366MHz.

Note 2. Model numbers reflect performance as described here: <http://www.amd.com/connectivity/solutions/geode/benchmark>.

Note 2. -40°C to 85°C is the optional Operating Case Temperature for the Geode LX800@0.9W and C5536. The standard Operating Case Temperature is 0°C to 85°C. Be sure to request the extended temperature version if required.

Note 3. Support for DDR2 available. Please see application note "AMD Geode™ LX Processor-Based System with ASint 90-DIMM Module" order #46950, posted on the AMD Embedded Developer Support Web site (<http://www.amd.com/dev>).

For system and board level products utilizing AMD processors, please visit www.amd.com/embedded/catalog

AMD EMBEDDED DISCRETE GRAPHICS

Model	Interface	Package	Memory	Engine/ Memory Clock	Power Management	TDP	Graphics	Video	DVI	LVDS	Analog RGB	DVO	TV	LVDS Display: Max Resolution	DVI Display: Max Resolution
ATI Radeon™ E2400	PCIe® x16¹	31mmx31mm BGA²	64-bit to 128MB GDDR3	Scalable to 600/700	PowerPlay™ 7.0¹ Technology	16W⁴	DirectX® 10.0 compliant Shader Model 4.0 Open GL 2.0 support	ATI Avivo™ HD, Universal Video Decoder for H.264 and VC-1 decode. Motion video decode for HD-DVD/Blu-ray technology MPEG 1/2/4 decode and encode acceleration	1 Single-link & 1 Dual-link³	18/24-bit Dual-Link	2 Integrated triple 10-bit DACs max Pixel CLK 400MHz	12-bit DDR or 24-bit SDR	YPbPr, NTSC and PAL	Dual-link: OXGA	Single-link: UXGA Dual-link: WUXGA

Note 1.

Note 2.

Note 3.

Note 4.

Note 5.

Note 6.

Can also operate in x8, x4, x2, x1 interface modes.

Also available in an MXM-II module with 256MB GDDR3 memory.

MXM-II module does not have PowerPlay™ 7.0 enabled.

TDP for MXM module is 16W.

The dual-link DVI interface of the E2400 is multiplexed with the dual-link LVDS interface.

While operating at the max/min P-states which can be dynamic or fixed through BIOS.

Note 1. Can also operate in x8, x4, x2, x1 interface modes.

Note 2. Also available in an MMX-II module with 256MB GDDR3 memory.

Note 3. MMX-II module does not have Powerplay™ 7.0 enabled.

Note 4. TDP for MMX module is 18W.

Note 5. The dual-link DVI interface of the E2400 is multiplexed with the dual-link LVDS interface.

Note 6. While operating at the max/min P-states which can be dynamic or fixed through BIOS.

Model	Devices	CPU Interface	Package	PCI Express®	PCI	Graphics	ATI Hybrid CrossFireX™	DVI/ HDMI	Display Port	LVDS	TV	DVO	SATA II	IDE	Power	USB	Audio	LPC	SPI	SMBus	Max GPIOs	Display: Max
AMD M690T	M690T/ SB800	1GHz HyperTransport™	21mm FCBGA/ 23mm FCBGA	1x8, 4x1 Gen 1	v2.3	DirectX® 9.0 WMV9	No	1 @ 1080i²	No	24-bit Dual-Channel	Yes	DVI & LVDS Transmitter Support¹	4, RAID 0, 1, 10 meets 1.0a spec	ATA 133	8W	10 v2.0	HD Audio, AC97 v2.3	2 LDRos	Yes	Yes	73	2048 x 1536
AMD M690E	M690E/ SB800	1GHz HyperTransport™	21mm FCBGA/ 23mm FCBGA	1x8, 4x1 Gen 1	v2.3	DirectX® 9.0 WMV9	No	2 @ 1080i¹	No	24-bit Dual-Channel	No	DVI & LVDS Transmitter Support¹	4, RAID 0, 1, 10 meets 1.0a spec	ATA 133	8W	10 v2.0	HD Audio, AC97 v2.3	2 LDRos	Yes	Yes	73	2048 x 1536
AMD 780E	780E/ SB710	2.6GHz HyperTransport™ 3.0	21mm FCBGA/ 21mm FCBGA	2x8 or 1x8, 6x1 Gen 2	v2.3	DirectX® 10.0 OpenGL 2.0, UVD 2.0	Yes	2@ 1080P²	Yes	24-bit Dual-Channel	No	No	6, RAID 0, 1, 10 meets 2.5 spec	ATA 133	13W	12 v2.0, 2 v1.1	HD Audio, AC97 v2.3	2 LDRos	Yes	Yes	73	2560 x 1600

Note 1. Capable display resolutions are influenced by the operating system driver, processor and memory selection.

Note 2. The PCI Express® x8 interface is multiplexed with a TMDS interface, enabling DVI or HDMI 1.2 with HDCP 1.1 support.

Note 3. The sideport memory interface of the M690T and M690E can be configured as a DVO to attach to an additional DVI, LVDS, or CRT transmitter.

Note 4. The LVDS interface of the M690E and 780E is multiplexed with a TMDS interface, enabling DVI or HDMI 1.2 (for the M690E) or HDMI 1.3b (for the 780E) with HDCP 1.1 support. This enables support for native dual DVI; however, only one HDMI interface may be enabled at a time.

AMD Geode™ Solutions Based Reference Design Kits																						
Name	Processor	Companion Device	Form Factor (Inches)	Video Output	OS ¹				I/O Connectors													
					Windows® XP/Vista	Windows CE	Linux®	Audio Out Channels	USB	PCI Slots	LPC Slots or Headers	Super I/O on Board	Ethernet on Board	Power Input	Serial ATA	IDE/UDMA	Serial Ports	PS/2 Keyboard/Mouse	Parallel Port	YDA		
LX ETX	AMD Geode™ LX 800@0.9W ²	AMD C5536	3.7x4.5	CRT/TFT	●	5.0	●		4				1	SVDD thru ETX conn.								
LX Ultra Value Client	AMD Geode™ LX 800@0.9W ²	AMD C5536	5.5x5	CRT	●	●	●	1	4		1		1	12VDC		●						
LX EPIC Single Board Computer	AMD Geode™ LX 800@0.9W or LX 700@0.8W ²	AMD C5536	4.5x6.5	CRT/TFT/LVDS	●	5.0	●	2	4	Mini PCI		●	1	Mini-ITX		●	2	●	●			
LX Network Attached Storage Processor	AMD Geode™ LX 800@0.9W or LX 700@0.8W ²	AMD C5536	Mini-ITX	CRT for debug only	●		●		3				1	ATX	1	●	2					

Note 1. OS support typically includes BIOS and drivers for audio, display, and bootloader if required.

Note 2. The Geode LX 800@0.9W processor operates at 500MHz and the Geode LX 700@0.8W processor operates at 433MHz. Model numbers reflect performance as described here: <http://www.amd.com/connectivity/solutions/geode/benchmark>.